Kulicke & Soffa Industries, Inc.

## Kulicke & Soffa Receives Supplier Award from STATS ChipPAC "Outstanding Award in Service and Support"

SINGAPORE--(BUSINESS WIRE)-- Kulicke and Soffa Industries, Inc. (NASDAQ: KLIC) ("Kulicke & Soffa", "K&S" or the "Company") today announced that STATS ChipPAC (SGX-ST Code: S24) honored the company with a Supplier Award on July 22, 2014.

STATS ChipPAC recognized K&S with an "Outstanding Award in Service and Support" for 2013. It honors material and equipment suppliers who distinguished themselves by providing excellent service, support, and responsiveness, while being aligned with and supporting their technology roadmap for the long term business requirements of STATS ChipPAC and their customers.

"We are pleased to recognize K&S with our Outstanding Award in Service and Support for 2013," said Cindy Palar, Senior Vice President of Strategic Operations, STATS ChipPAC. "K&S delivered a strong performance in 2013 and continues to be an important strategic supplier for our copper wire bond business. Their technology and equipment is well aligned with our customer base and initiatives, such as the UPH improvement program, that has been an important advantage for STATS ChipPAC and our customers. We value the regular and timely technology updates to our operations team every quarter and the ongoing training that K&S provides to each of our manufacturing sites. K&S responsiveness, excellent sales support, and overall flexibility in delivery dates for our factories have been appreciated."

Mr. Bruno Guilmart, President and CEO of the Company said, "As we continue to focus on delivering technologically advanced, innovative products and total solutions to our customers, it's an honor to be recognized for our efforts in the past year. We thank STATS ChipPAC for this recognition, and we look forward to a continued strong partnership in the future."

## About Kulicke & Soffa

Kulicke & Soffa (NASDAQ: KLIC) is a global leader in the design and manufacture of semiconductor and LED assembly equipment. As a pioneer in this industry, K&S has provided customers with market leading packaging solutions for decades. In recent years, K&S has expanded its product offerings through strategic acquisitions, adding wedge bonding and a broader range of expendable tools to its core ball bonding products. Combined with its extensive expertise in process technology, K&S is well positioned to help customers meet the challenges of assembling the next-generation semiconductor and LED devices. (www.kns.com)

## About STATS ChipPAC Ltd.

STATS ChipPAC Ltd. (SGX-ST Code: S24) is a leading service provider of semiconductor packaging design, assembly, test and distribution solutions in diverse end market applications including communications, digital consumer and computing. With global headquarters in Singapore, STATS ChipPAC has design, research and development, manufacturing or customer support offices throughout Asia, the United States and Europe. STATS ChipPAC is listed on the SGX-ST. Further information is available at <a href="https://www.statschippac.com">www.statschippac.com</a>. Information contained in this website does not constitute a part of this release.

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